

B. Amendment to the Claims

Please cancel claim 8 without prejudice or disclaimer.

Please amend claims 7 and 9-11 as follows.

1. (Original) An electrode and wiring forming method, comprising:  
a base pattern forming step of forming a base pattern on a substrate;  
an absorbing step of absorbing an organic metallic compound into the base pattern; and  
a baking step of baking the base pattern in which the organic metallic compound is absorbed,  
wherein the base pattern forming step includes:  
a step of applying a photosensitive resin containing a water-soluble photosensitive resin component and a water-soluble metallic compound onto the substrate;  
and  
a step of exposing the photosensitive resin.
2. (Original) An electrode and wiring forming method according to claim 1, wherein a compounding ratio of the water-soluble metallic compound to the photosensitive resin component is 1.0 % by weight to 20 % by weight.
3. (Original) An electrode and wiring forming method according to claim 2, wherein the water-soluble metallic compound is a water-soluble metallic compound including rhodium, bismuth, ruthenium, vanadium, chromium, tin, lead, or silicon.

4. (Original) An electrode and wiring forming method according to claim 2, wherein the organic metallic compound is a complex and a ligand thereof is a nitrogen-containing compound.

5. (Original) An electrode and wiring forming method according to claim 4, wherein the nitrogen-containing compound is a nitrogen-containing compound having at most 8 carbon atoms.

6. An electrode and wiring forming method according to claim 2, wherein the organic metallic compound is a platinum complex.

7. (Currently Amended) A base pattern forming material for electrode and wiring material absorption comprising a water-based solution containing a water-soluble photosensitive resin component and a water-soluble metallic compound, wherein a compounding ratio of the water-soluble metallic compound to the photosensitive resin component is from 1.0 to 20 % by weight.

8. (Cancelled)

9. (Currently Amended) A base pattern forming material for electrode and wiring material absorption according to claim 7 [[8]], wherein the water-soluble metallic compound is a water-soluble metallic compound including rhodium, bismuth, ruthenium, vanadium, chromium, tin, lead, or silicon.

10. (Currently Amended) A base pattern forming material for electrode and wiring material absorption according to claim 7 [[8]], wherein the water-soluble photosensitive resin component is one of a polyvinyl alcohol-based resin and a polyvinyl ~~pyrrolidone-based~~ pyrrolidone-based resin.

11. (Currently Amended) A method of manufacturing an image-forming apparatus including a plurality of electron-emitting devices and an image-forming member for forming an image by irradiation of electron beams emitted from the electron-emitting devices, comprising:

forming said plurality of electron-emitting devices and said image-forming member,

wherein forming at least one of an electrode and a wiring is formed by the method according to claim 1.